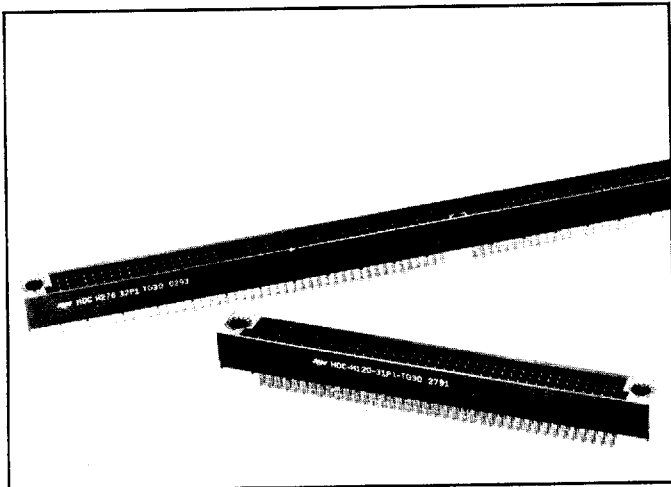


PCB/Backplane Headers

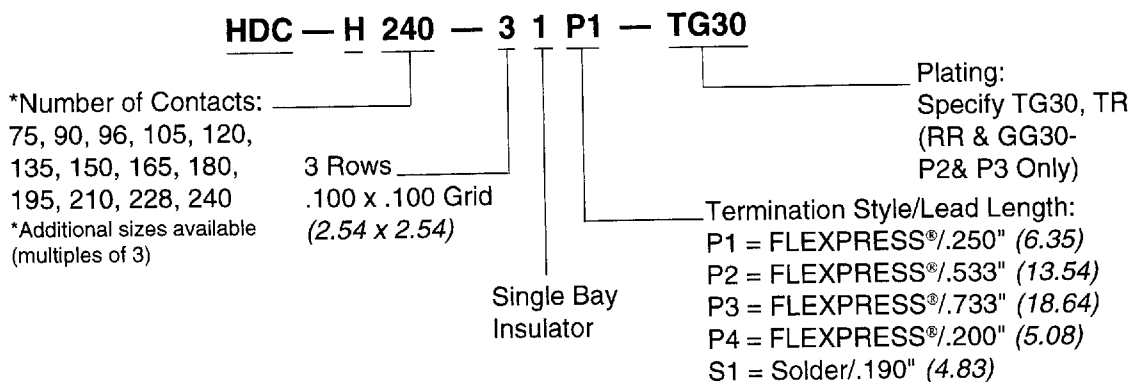
Single or Dual Bay
HDC - H3 Series



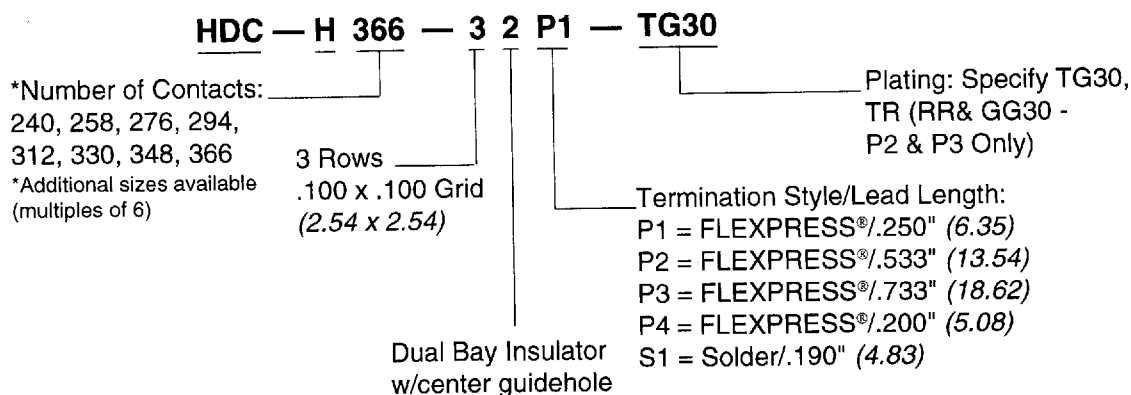
- High density up to 240 contacts
- Dual FLEXPRESS® contacts are front and rear repairable (pages 339-340 for contact data)
- Mates with 3 row sockets
- EMLB grounding contacts allow "hot board" replacement (see page 312)

DIN/HDC
BACKPLANE

How to Order 3 Row Single Bay Headers



How to Order 3 Row Dual Bay Headers



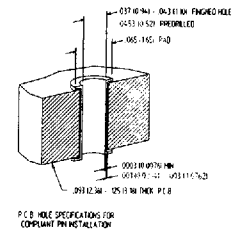
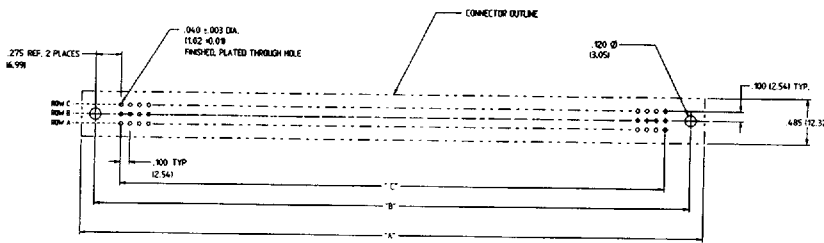
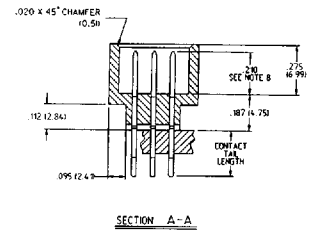
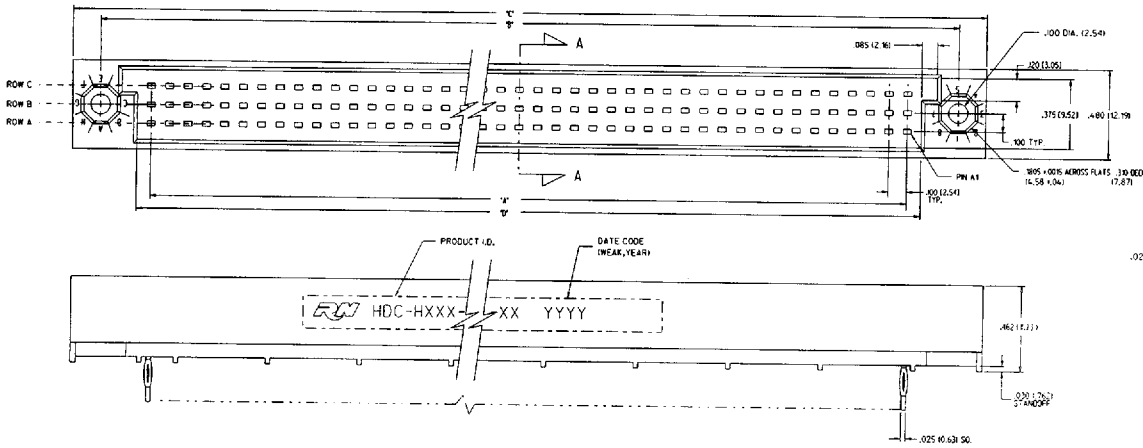
HIGH DENSITY CONNECTORS



3 Row Single Bay

DESCRIPTION	TOTAL POSITIONS	"A" DIM	"B" DIM	"C" DIM	"D" DIM
HDC-H075-31PX-XX	75	2.400 (60.96)	2.950 (74.93)	3.250 (82.55)	2.550 (64.77)
HDC-H090-31PX-XX	90	2.900 (73.66)	3.450 (87.63)	3.750 (95.25)	3.050 (77.47)
HDC-H096-31PX-XX	96	3.100 (78.74)	3.650 (92.71)	3.950 (100.33)	3.250 (82.55)
HDC-H105-31PX-XX	105	3.400 (86.36)	3.950 (100.33)	4.250 (107.95)	3.550 (90.17)
HDC-H120-31PX-XX	120	3.900 (99.06)	4.450 (113.03)	4.750 (120.65)	4.050 (102.87)
HDC-H135-31PX-XX	135	4.400 (111.76)	4.950 (125.73)	5.250 (133.35)	4.550 (115.57)
HDC-H150-31PX-XX	150	4.900 (124.46)	5.450 (138.43)	5.750 (146.05)	5.050 (128.27)
HDC-H165-31PX-XX	165	5.400 (137.16)	5.950 (151.13)	6.250 (158.75)	5.550 (140.97)
HDC-H180-31PX-XX	180	5.900 (149.86)	6.450 (163.83)	6.750 (171.45)	6.050 (153.67)
HDC-H195-31PX-XX	195	6.500 (162.56)	6.950 (176.53)	7.250 (184.15)	6.550 (166.37)
HDC-H210-31PX-XX	210	6.900 (175.26)	7.450 (189.23)	7.750 (196.85)	7.050 (179.07)
HDC-H228-31PX-XX	228	7.500 (190.50)	8.050 (204.47)	8.350 (212.09)	7.650 (194.31)
HDC-H240-31PX-XX	240	7.900 (200.66)	8.450 (214.63)	8.750 (222.25)	8.050 (204.47)

UNIHDC BACKPLANE

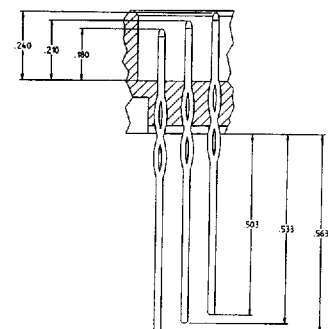
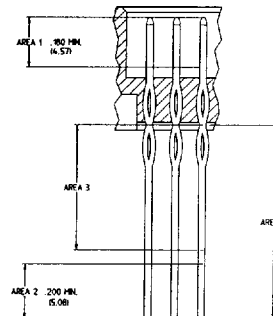


RECOMMENDED P.C.B. HOLE PATTERN

Plating Description:

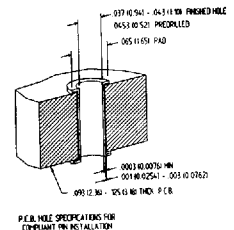
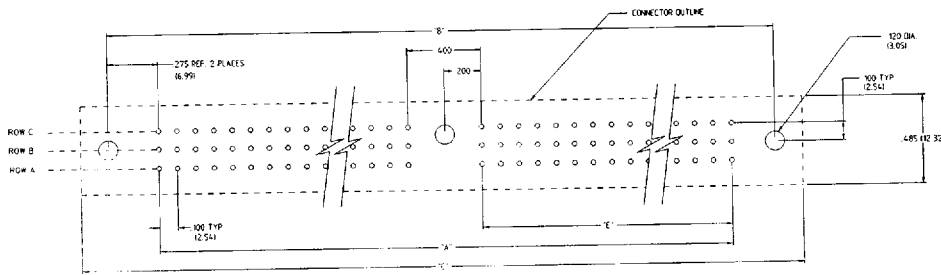
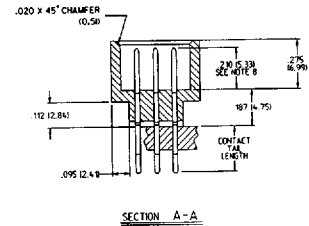
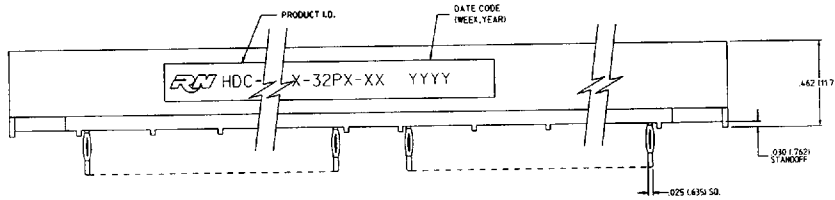
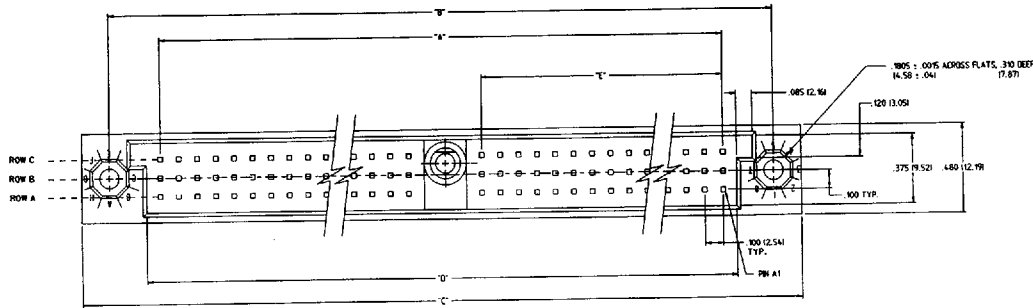
- TG30** = 30 μinch (.762 μm) minimum Gold on Area 1.
100 μinch (2.54 μm) minimum Tin /Lead on Area 4.
- TR** = 10 μinch (.254 μm) minimum ROBEX® on Area 1.
100 μinch (2.54 μm) minimum Tin /Lead on Area 4.
- RR** = 10 μinch (.254 μm) minimum ROBEX® on Area 1 and Area 2.
100 μinch (2.54 μm) minimum Tin/Lead on Area 3.
- GG30** = 30 μinch (.762 μm) minimum Gold on Area 1.
10 μinch (.254 μm) minimum gold on Area 2
100 μinch (2.54 μm) minimum Tin /Lead on Area 3.

All options include:
50 μinch (1.27 μm) minimum Nickel underplate.

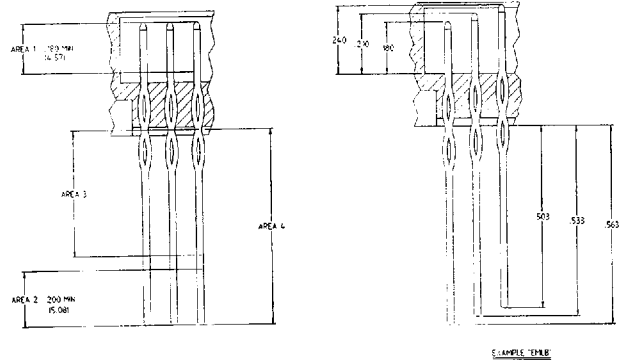


EXAMPLE TOLERANCES

DESCRIPTION	TOTAL POSITIONS	"A" DIM	"B" DIM	"C" DIM	"D" DIM	"E" DIM
HDC-H228-32PX-XX	228	7.800 (198.12)	8.350 (212.09)	8.650 (219.71)	7.950 (201.93)	3.700 (93.98)
HDC-H240-32PX-XX	240	8.200 (208.28)	8.750 (222.25)	9.050 (229.87)	8.350 (212.09)	3.900 (99.06)
HDC-H258-32PX-XX	258	8.800 (215.90)	9.350 (229.87)	9.650 (237.49)	8.950 (219.71)	4.200 (106.68)
HDC-H276-32PX-XX	276	9.400 (231.14)	9.950 (245.22)	10.250 (252.73)	9.550 (234.95)	4.500 (114.30)
HDC-H294-32PX-XX	294	10.000 (246.38)	10.550 (260.35)	10.850 (267.97)	10.150 (250.19)	4.800 (121.92)
HDC-H312-32PX-XX	312	10.600 (261.62)	11.150 (275.59)	11.450 (283.21)	10.750 (265.43)	5.100 (129.54)
HDC-H330-32PX-XX	330	11.200 (276.86)	11.750 (290.83)	12.050 (298.45)	11.350 (280.67)	5.400 (137.16)
HDC-H348-32PX-XX	348	11.800 (292.10)	12.350 (306.07)	12.650 (313.69)	11.950 (295.91)	5.700 (144.78)
HDC-H366-32PX-XX	366	12.400 (307.34)	12.950 (321.31)	13.250 (328.93)	12.550 (311.15)	6.000 (152.40)



RECOMMENDED P.C.B. HOLE PATTERN



Plating Description:

- TG30 = 30 μ inch (.762 μ m) minimum Gold on Area 1.
100 μ inch (2.54 μ m) minimum Tin /Lead on Area 4.
- TR = 10 μ inch (.254 μ m) minimum ROBEX® on Area 1.
100 μ inch (2.54 μ m) minimum Tin /Lead on Area 4.
- RR = 10 μ inch (.254 μ m) minimum ROBEX® on Area 1 and Area 2.
100 μ inch (2.54 μ m) minimum Tin/Lead on Area 3.
- GG30 = 30 μ inch (.762 μ m) minimum Gold on Area 1.
10 μ inch (.254 μ m) minimum gold on Area 2
100 μ inch (2.54 μ m) minimum Tin /Lead on Area 3.

All options include:
50 μ inch (1.27 μ m) minimum Nickel underplate.

DIN/HDC
BACKPLANE

MECHANICAL & ELECTRICAL SPECIFICATIONS

Insertion Force (Avg. per contact maximum): HDC-RXXX = 2.6 oz; HDC-SXXX = 2.0 oz
Withdrawal Force (Avg. per contact minimum): HDC-RXXX = .75 oz; HDC-SXXX = .50 oz
Mating Force: 0.1 lb x number of contacts
Contact Resistance: 20 milliohms maximum
Insulation Resistance: 1000 megohms minimum
Test Voltage: 900 Volts AC RMS
Current Rating: 2 amperes/contact

ENVIRONMENTAL SPECIFICATIONS

Temperature Rating (Continuous): -55°C to +125°C
Shock: Per MIL-STD-1344, Method 2004
Vibrations: Per MIL-STD-1344 Method 2005
Humidity: Per MIL-STD-1344 Method 1002, Type II
Temperature: Withstands SMT soldering temperatures for 60+ seconds
 (HDC-RXXX and HDC-SXXX)

MATERIAL SPECIFICATIONS

	Receptacle (HDC-RXXX, HDC-SXXX)	Header (HDC-HXXX, HDC-PXXX)
Body:	Black, liquid crystal polymer	Black, glass filled thermoplastic
Oxygen Index Rating:	42%	28%
Contact:	Phosphor Bronze (HDC-RXXX) Beryllium Copper (HDC-SXXX)	Copper Alloy
Flammability:	UL 94V-0	UL 94V-0

Plating Description:

Suffix TG30 = 30 μ inch (.762 μ m) minimum Gold on mating area.
 100 μ inch (2.54 μ m) minimum Tin/Lead on compliant and terminal areas.

TR = 10 μ inch ROBEX® [7 μ inch (.178 μ m)
 Palladium Nickel with 3 μ inch (.076 μ m) minimum
 Gold flash] on mating area.
 100 μ inch (2.54 μ m) minimum Tin/Lead on
 compliant and terminal areas.

*** GG30 =** 30 μ inch (.762 μ m) minimum Gold on mating area.
 10 μ inch (.254 μ m) minimum Gold on terminal area.
 100 μ inch (2.54 μ m) minimum Tin/Lead on compliant area.

***RR =** 10 μ inch ROBEX® [7 μ inch (.178 μ m) minimum
 Palladium Nickel with 3 μ inch (.076 μ m)
 Gold flash] on mating area and terminal area.
 100 μ inch (2.54 μ m) minimum Tin/Lead on compliant area.

All options include an underplate of 50 μ inch (1.27 μ m) minimum Nickel.

*Available with P2 & P3 Terminations only.